



Material Content Data Sheet



Sales Product Name		TLD5541-1QV		Issued		1. August 2018		
MA#		MA001680142						
Package		PG-VQFN-48-31		Weight*		129.27 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.790	1.38	1.38	13850	13850
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		139	
	non noble metal	zinc	7440-66-6	0.072	0.06		554	
	non noble metal	iron	7439-89-6	1.433	1.11		11087	
wire	non noble metal	copper	7440-50-8	58.193	45.02	46.20	450182	461962
	non noble metal	copper	7440-50-8	0.595	0.46	0.46	4602	4602
	encapsulation	organic material	carbon black	1333-86-4	0.190	0.15		1470
encapsulation	plastics	epoxy resin	-	8.042	6.22		62210	
	inorganic material	silicondioxide	60676-86-0	55.088	42.62	48.99	426163	489843
leadfinish	non noble metal	tin	7440-31-5	2.596	2.01	2.01	20086	20086
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4749	4749
glue	plastics	epoxy resin	-	0.146	0.11		1129	
	noble metal	silver	7440-22-4	0.489	0.38	0.49	3779	4908
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com